Community Led Hyperscale Open Innovation

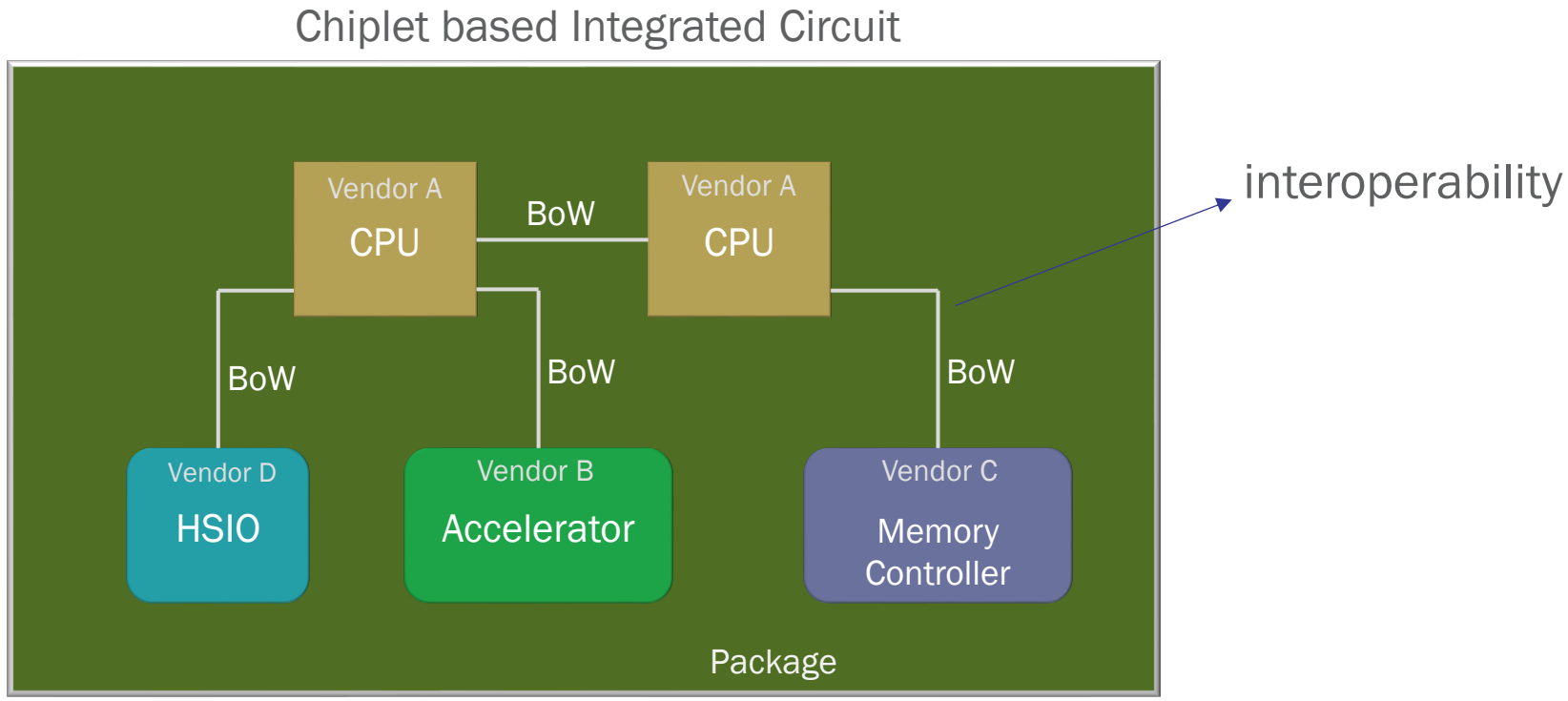
OCP – ODSA Project

Open Platform Development for BoW PHY Interoperability Testing

Jayaprakash Balachandran

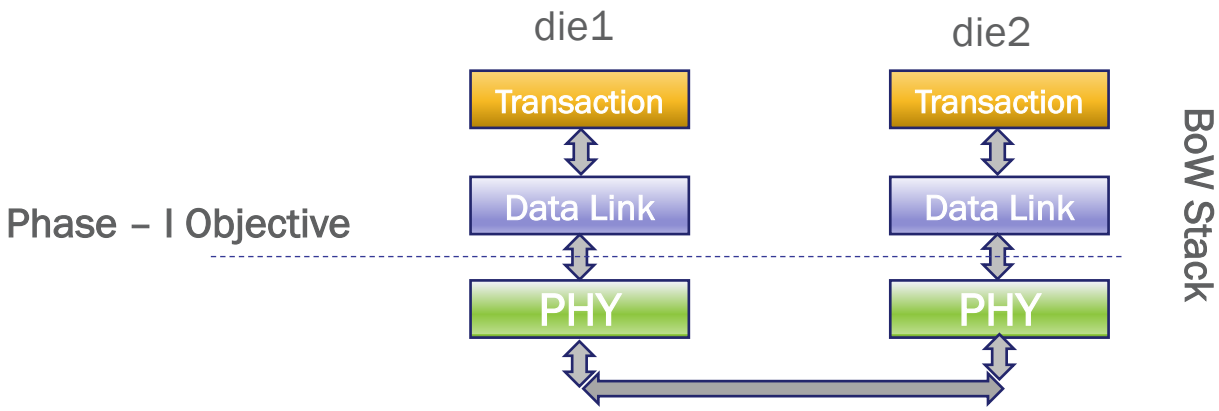
Cisco inc

Interoperability Key for Chiplet based IC Designs



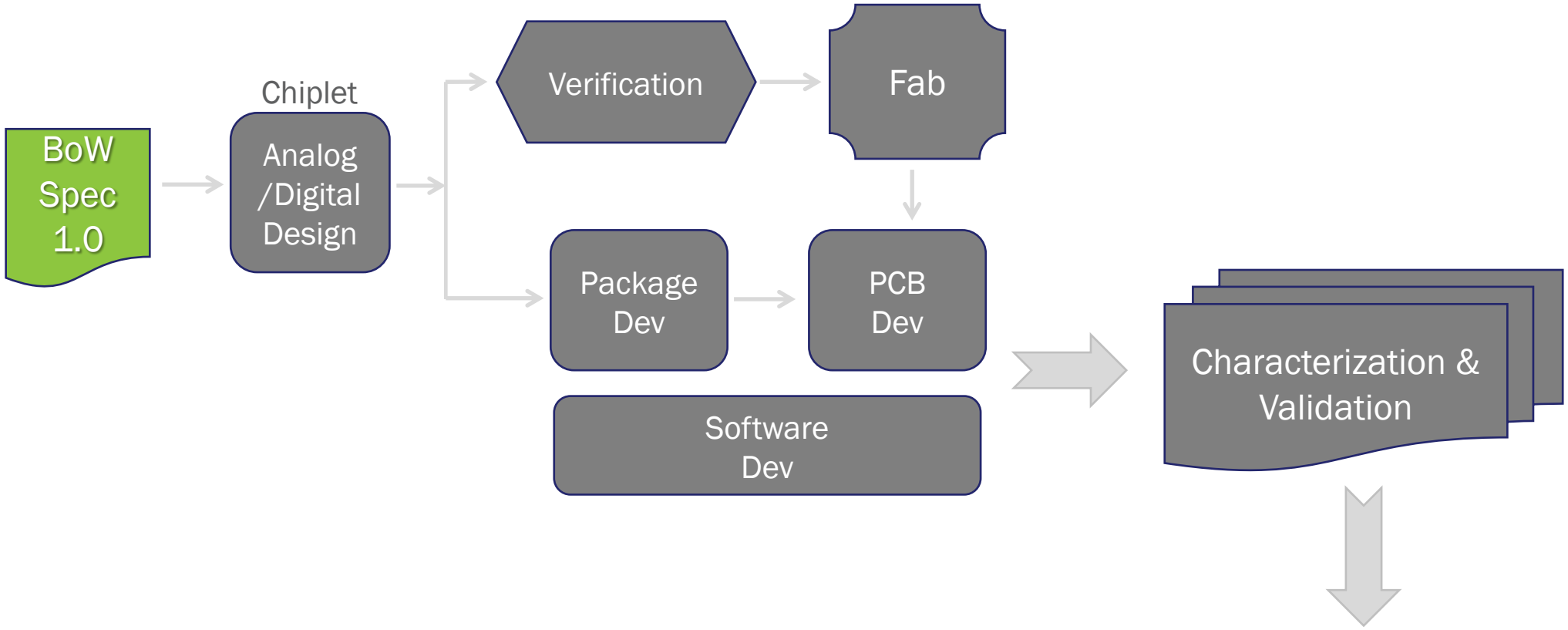
Objective

- Demonstrate interoperability between two independent PHY implementations based on BoW spec 1.0



- Bring confidence to adopters

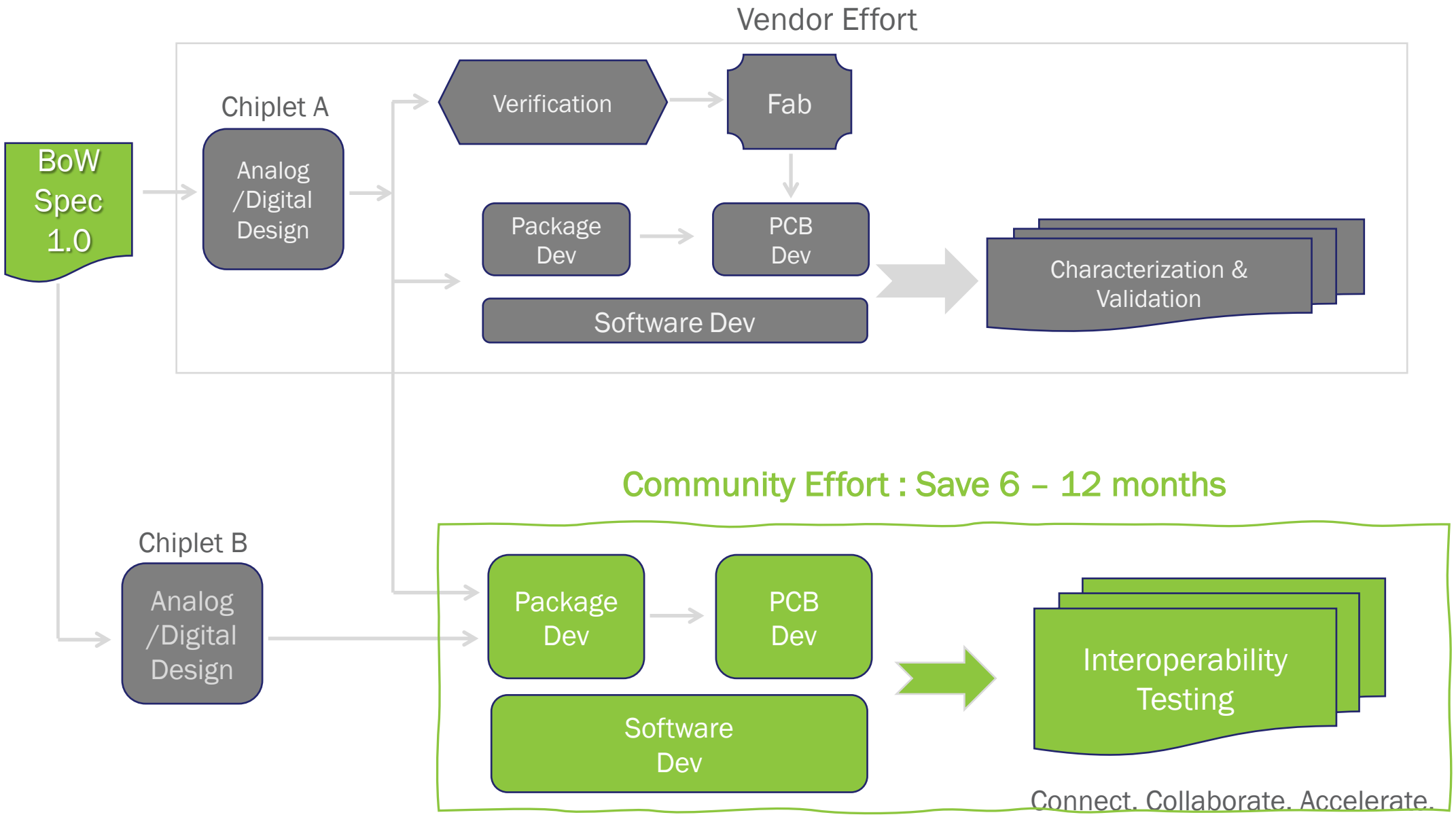
Interoperability Testing Challenge



+ 6 -12 months

Connect. Collaborate. Accelerate.

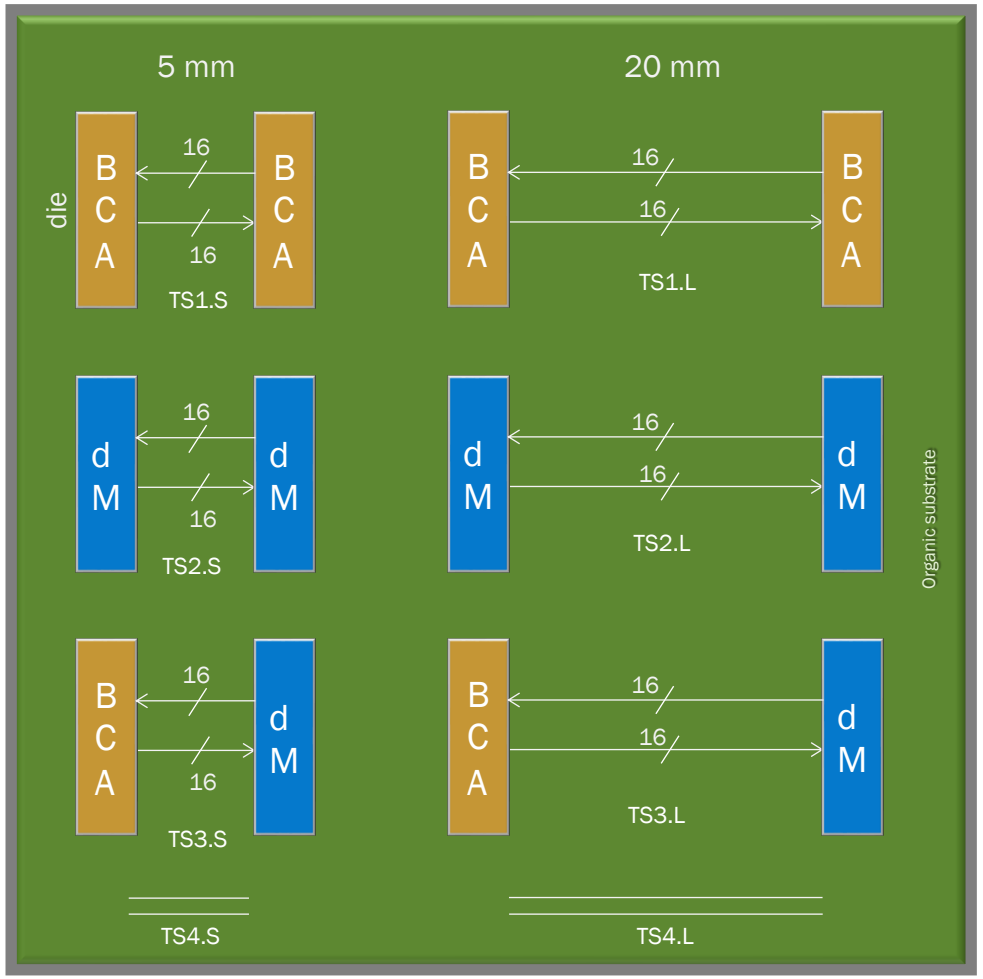
Community Effort for Interop Testing



BoW Interop Workstream Goals

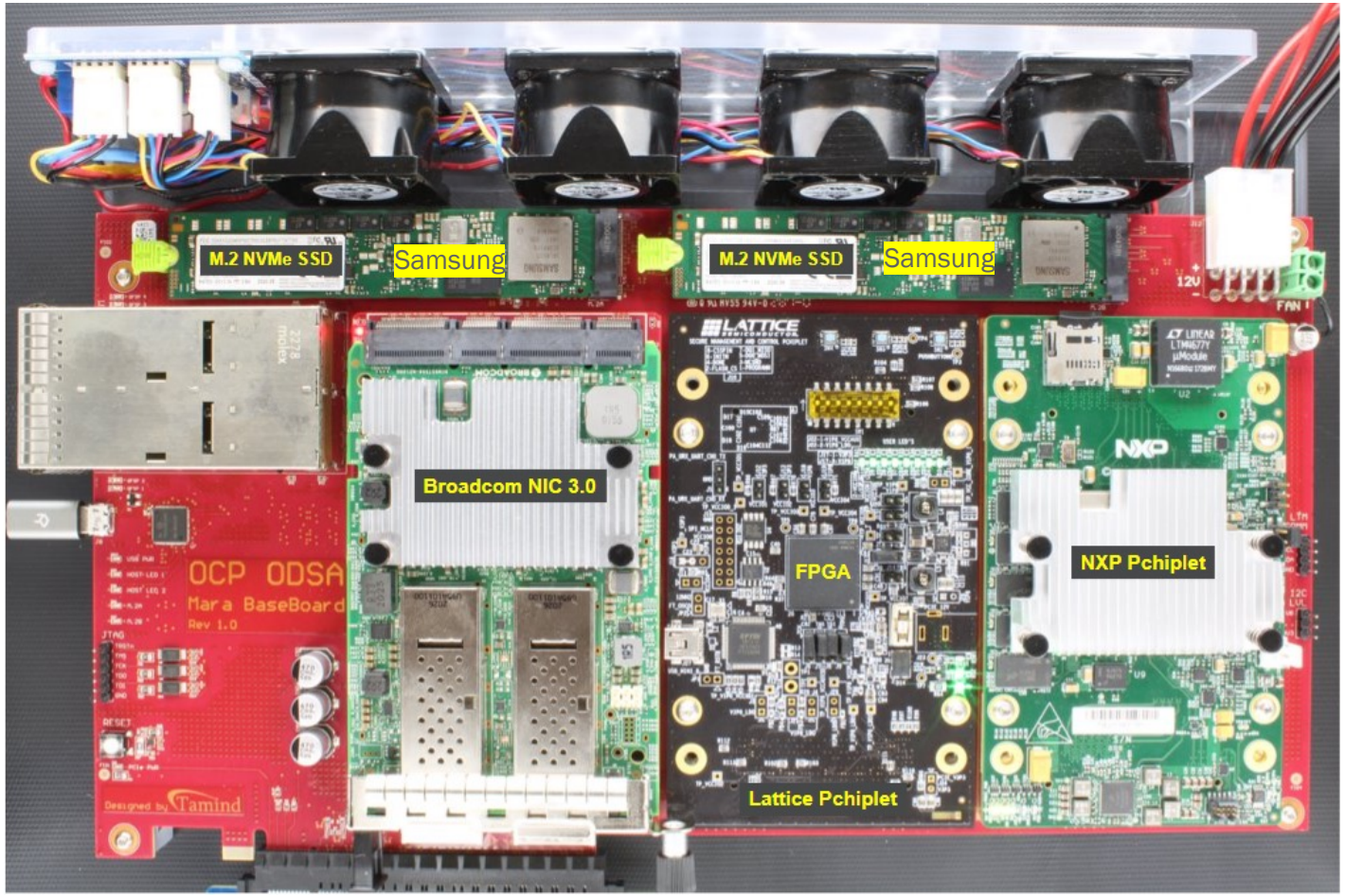
- Develop an Open Organic Substrate and a PCB to test interoperability between two different PHY Implementations based on BoW Spec 1.0
- Agree on a set of Interoperability and Compliance tests
- Agree on the Test Methods
- Define a Vendor neutral SW APIs for BoW PHY initialization, monitoring and Testing
- Develop & Publish Implementation Guidelines for Various D2D Layout Scenarios
- Publish Interop Test Report after Detailed Characterization

BoW Interop Substrate



BCA – Blue Cheetah Analog
dM – dMatrix

Leverage ODSA Accelerator Prototyping Platform for Interop Testing

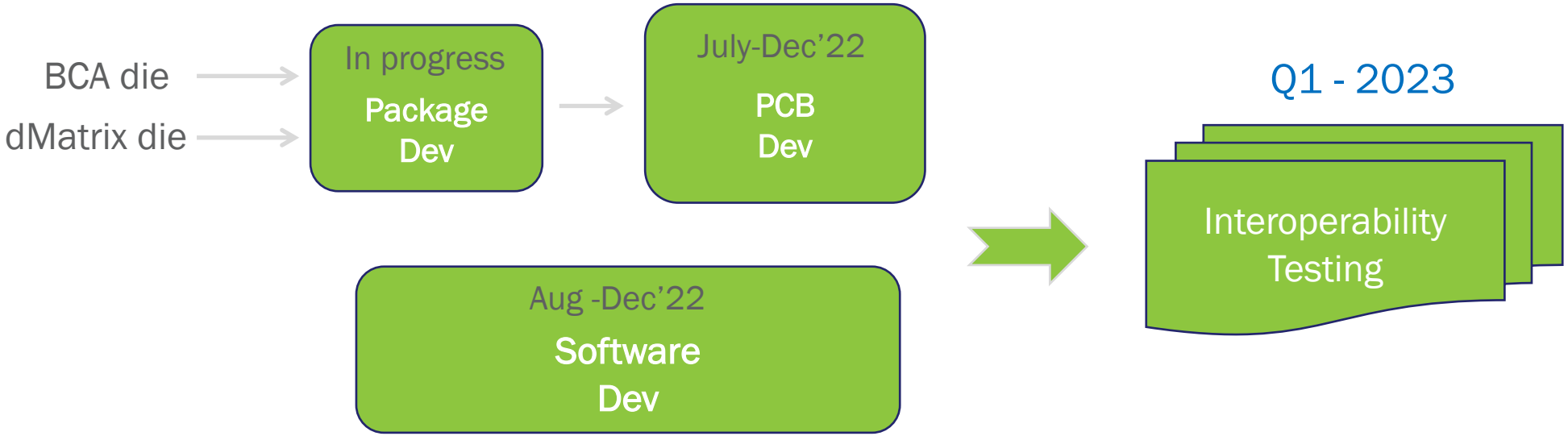


BoW Interop Community

Connect. Collaborate. Accelerate.

Schedule

- Fab out: July'22
- Supply chain risk mitigation plan



Summary

- Facilitate BoW Deployments in commercial products through Interop Testing and Validation
  - First of its kind for Chiplets
- Bring Confidence to the adopters
- Community driven Effort

Questions

Connect. Collaborate. Accelerate.